

ABSTRACT

Method and apparatus for cutting a substrate using laser irradiation.

5 The invention relates to a method and apparatus for cutting a substrate using laser
irradiation. A laser beam is scanned over a substrate. The beam ablates a first layer of the
substrate. The beam is then refocused onto the newly revealed second layer and a further
pass is performed. The process is repeated until complete separation occurs. The method
and apparatus are particularly suitable for singulation of IC packages.

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